Abstract

Apparatus and method for removing at least one chip-type semiconductor component from a film

The application relates to an apparatus and a method for operating said apparatus for removing at least one chip-type semiconductor component from an adhesive film, comprising the following steps: arranging the lifting device with respect to the film, wherein a contact region of the lifting device bears against a second main surface of the film, opposite a chip-type semiconductor component that is arranged on a first main surface and is to be lifted off; applying to a plurality of suction cutouts of the lifting device, by means of an assigned vacuum regulating device, a constant value of a vacuum for all the suction cutouts or different values of the vacuum for different suction cutouts or groups of suction cutouts; partially deforming the film in the contact region by lifting the film by means of lifting means, arranged in assigned cutouts of the lifting device; removing the at least one semiconductor component from the film by means of a removal device.

Figure (1)